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IPC-4554

Specification for Immersion Tin Plating for Printed Circuit Boards

IPC-4554

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A standard developed by IPC

3000 Lakeside Drive, Suite 309S, Bannockburn, IL 60015-1249
Tel. 847.615.7100 Fax 847.615.7105
www.ipc.org

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Developed by the Plating Processes Subcommittee (4-14) of the
Fabrication Processes Committee (4-10) of IPC

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Contact:

IPC
3000 Lakeside Drive, Suite 309S
Bannockburn, Illinois
60015-1249
Tel 847 615.7100
Fax 847 615.7105

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Fabrication Processes Committee	Plating Processes Subcommittee	Technical Liaisons of the IPC Board of Directors
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Plating Processes Subcommittee		
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Gail Auyeung, Celestica International Inc.	Marion Graybeal, Consultant	Gary C. Roper, One Source Group, Eagle Circuits Inc.
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Lee Burger, Electrochemicals Inc.	Kuldip Johal, Atotech USA Inc.	Atamjit Singh, Unitech Industries Inc.
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Michael V. Carano, Electrochemicals Inc.	Thomas E. Kemp, Rockwell Collins	Joseph Smetana, Alcatel-Lucent
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Phillip Chen, L-3 Communications Electronic Systems	Bridget Lawrence, Pentaplex Inc.	Bill Starmann, Raytheon Company
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Gordon Davy, Northrop Grumman Corporation	Ramesh Mohabir, Celestica International Inc.	Timothy L. Wells, Endicott Interconnect Technologies Inc.
Steve Dunford, Nokia Networks	Keith G. Newman, Sun Microsystems Inc.	Karl F. Wengenroth, Enthone Inc. - Cookson Electronics
C. Don Dupriest, Lockheed Martin	Mario Orduz, UIC/Uyemura International Corp.	John E. Williams, Raytheon Company
Richard M. Edgar, Tec-Line Inc.	Anders P. Pedersen, Harris Corporation, GCSO	Yung-Herng Yau, Enthone Inc. - Cookson Electronics
Theodore Edwards, Dynaco Corp.	Mike Pfeifer, Motorola Inc. ACES	
Dennis Fritz, MacDermid, Inc.	Jim R. Reed, Dell Inc.	

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